5962-E580

		▼			00761
			REVISIONS		
	LTR	DESC	RIPTION	DATE	APPROVED
		Add case outline Change to milita Change A.C. para TLHLL, TAVLL. Change drawing C Editorial change	ry drawing format. meters TAVDV, TRLDV, AGE to 67268.	07	Mai/Ar Je
				•	
,					
CURRENT CAC	GE CODE	67268			
PAGE REV STATUS REV F		A A A A A	A A A A A A	+-+-	
OF PAGES PAGES 1 Defense Electronics Supply Center Dayton, Ohio	PREPARED BY	Jamison	MILITARY This drawing is available Departments and	DR/ able for u	se by
Original date of drawing: 18 November 1985	APPROVED B	IDENT. NO.	GATE, MONOL	TS, DIGIT OCONTROLL ITHIC	AL, N-CHANNEL, ER, SILICON
AMSC N/A		4933	PAGE 1	063 0F	16

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

DESC FORM 193 MAY 86

1. SCOPE			
1.1 Scope. This drawing describes dev $1.2.1$ of MIL-STD-883, "Provisions for the devices".	ice requireme e use of MIL-	nts for class B STD-883 in conju	microcircuits in accordance with nction with compliant non-JAN
1.2 Part number. The complete part nu	mber shall be	as shown in the	following example:
<u>85063</u> <u>01</u>	-	Z T	X T
Drawing number Device	Tuno	Casa autima	Lead finish
Drawing number Device (1.2.		Case outline (1.2.2)	(3.3)
1.2.1 <u>Device type</u> . The device type sh	all identify	the circuit fund	tion as follows:
Device type Generic	number	Circ	it
01 80	97	NMOS 16-bit Mic	rocontroller
1.2.2 <u>Case outlines</u> . The case outline follows:	s shall be as	designated in a	ppendix C, MIL-M-38510 and as
Outline letter		Case outline	
Y Z	P-AC, 68-p	68-lead ceramic in hermetic gri	larray package
1.3 Absolute maximum ratings.	#196	PGA, GEFIN	// ×#
Supply voltage Operating voltage range Case temperature under bias 1/ Storage temperature range Voltage from any pin to V _{SS} or ANG Average output current (any pin) - Maximum power dissipation (P _D) - Lead temperature (soldering, 10 se Maximum junction temperature Thermal resistance, junction-to-ca Case Y	ind	7.0 V dc maximum -0.3 V dc to +72-55°C to +125°C -65°C to +150°C -0.3 V dc to 7.0 10 mA maximum 1.5 W +300°C +200°C 5°C/W See MIL-M-38510	0 V dc
1.4 Recommended operating conditions.			
Case temperature under bias (T _C) Digital supply voltage (V _{CC}) Analog supply voltage (V _{REF}) Oscillator frequency (f _{OSC}) Power down supply voltage (V _{PD}) - Resolution 2/ Accuracy 2/ Differential nonlinearity 2/ Integral nonlinearity 2/ Channel-to-channel matching Crosstalk (dc to 100 kHz)		$\begin{array}{c} -55^{\circ}\text{C} &< \text{T}_{\text{C}} &< +12\\ 4.50\text{V}_{\text{CC}} &-0.3&< \\ 4.50\text{V}_{\text{CC}} &-0.3&< \\ 6.0\text{MHz} &< fosc&< \\ 4.50\text{V} &< \text{VpD} &< \frac{1}{2}\\ \pm .001\text{VREF} & \frac{3}{2}/\\ \pm .002\text{VREF} & \text{maxin}\\ \pm .004\text{VREF} & \text{maxin}\\ \pm 1\text{LSB} & \frac{4}{2}/\\ -60\text{dB} & \text{maxinum} \end{array}$	um 3/ um <u>3</u> /
 1/ Case temperature is "instant on". 2/ Testing is done at V_{REF} = 5.120 V. 3/ Guaranteed but not tested. 4/ Not tested or guaranteed. 			
MILITARY DRAWING	SIZE A		DWG NO. 85063
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO		REV A	PAGE 2

2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtain from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
 - 3. REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Block diagram. The block diagram shall be as specified on figure 2.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 3.
 - 3.2.3 Case outline. The case outline shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.4 <u>Marking</u>. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

MILITARY DRAWING	SIZE A	· · · · · · · · · · · · · · · · · · ·	DWG NO	85063	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO		REV		PAGE 3	

DESC FORM 193A

FEB 86

	TABLE I. Electrical performance characteristics.										
Test	Symbol	Conditions	Group A		mits	Unit					
		-55°C <u><</u> T _C <u><</u> +125°C	subgroups	Min	Max						
Input low voltage (except RESET)	VIL	 	1, 2, 3	-0.3 <u>1</u> /	+0.8	٧					
Input low voltage, RESET	V _{IL1}		1, 2, 3	-0.3 <u>1</u> /	+0.7	V					
Input high voltage (except RESET, NMI, XTAL1)	IV _{IH}	 	1, 2, 3	2.0 	V _{CC} +0.5	V					
Input high voltage, RESET, NMI, XTAL1	v _{IH1}		1, 2, 3	2.4	Y _{CC} +0.5	٧					
Output low voltage	V _{OL}	<u>2</u> /	1, 2, 3	 	0.5	V					
Output high voltage	v _{OH}	3/	1, 2, 3	2.4		٧					
V _{CC} supply current	Icc	 All outputs disconnected	1, 2, 3	 	200	 mA 					
VpD supply current	IPD	Normal operation and power-down	1, 2, 3		1	 mA 					
V _{REF} supply current	IREF	All bits	1, 2, 3		10	l mA					
Input leakage current to all pins of HSI, PO, P3, P4, and to P2.1	ILLI	V _{IN} = 0 to V _{CC} 4/	1, 2, 3		±10	μ Α					
Input high current to	IIH	V _{IH} = 2.4 V	1, 2, 3	 	100	μ Α					
Input low current to all pins of P1, and to P2.6, P2.7	IIL	V _{IL} = 0.45 V	1, 2, 3		-100	μ Α					

See footnotes at end of table.

MILITARY DRAWING	SIZE		DWG NO.	85063	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO		REV A		PAGE	4

DESC FORM 193A FEB 86

- 1

TABL	E I. <u>El</u>	ectrical performance characterist	ics - Conti		mits	
Test	Symbol	Conditions -55°C \le T _C \le +125°C	Group A		Max	 Unit
Input low current to RESET	IIL1	V _{IL} = 0.45 V	1, 2, 3	 	 -2 	l mA
Input low current P2.2, P2.3, P2.4, READY	I _{IL2}	V _{IL} = 0.45 V	1, 2, 3	i 	-50 	 μ Α
Pin capacitance (any pin to V _{SS})	C _s		4 4	 	10	l pF
Oscillator frequency	FXTAL	Oscillator frequency = 12 MHz Load capacitance on output	9, 10, 11	6.0	12.0	MHz
1/Oscillator frequency	TOSC	pins = 80 pF See figure 3 		 83 	166	ns
CLKOUT period $\underline{5}$ /, $\underline{8}$ /	ТСНСН	 -		 3Tosc-30	 3Tosc+30	ns
CLKOUT high time	TCHCL	- 		Tosc-20	Tosc+20	ns
CLKOUT low to ALE high	TCLLH			 -30 	+30	ns
ALE low to CLKOUT high	TLLCH	 	 	Tosc-20	Tosc+40	ns
ALE pulse width	TLHLL	 	 	Tosc-30	Tosc+20	ns
Address valid to end of ALE	 TAVLL	 		Tosc-60 	 	l ns
End of ALE to RD or WR active	TLLRL	 	 	Tosc-20	1	l ns
End of ALE to address invalid <u>8</u> /	TLLAX	 		Tosc-20	 	ns
WR pulse width	 TWLWH] 	 	2Tosc-35	1	ns

See footnotes at end of table.

MILITARY DRAWING	SIZE		DWG NO	85063	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO		REV	A	PAGE 5	

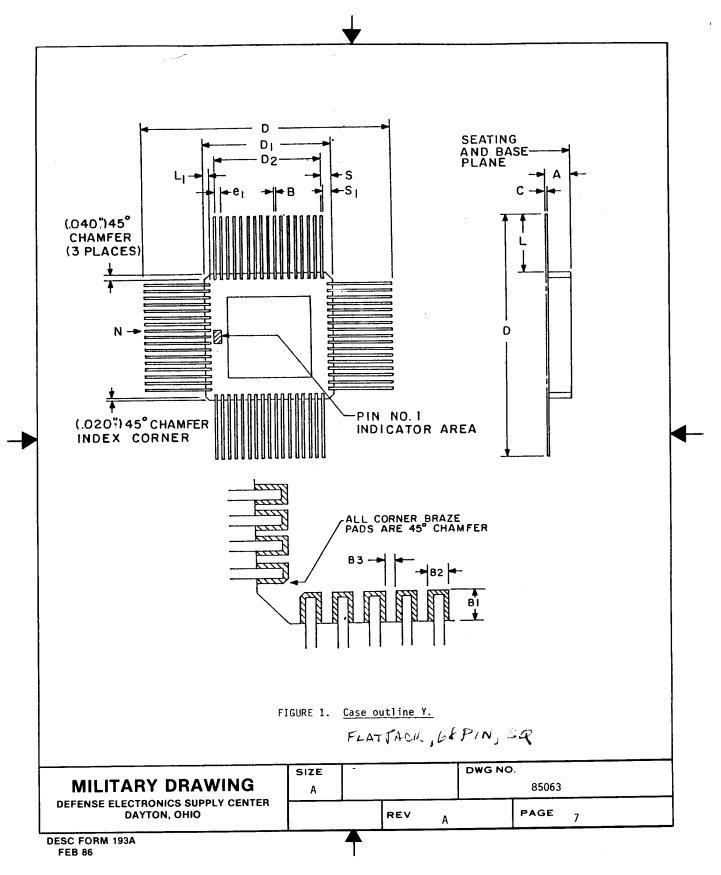
Test	Symbol	Conditions	Group A	Li		Unit
		-55°C <u><</u> T _C <u><</u> +125°C	subgroups	Min	Max	
Output data valid to end of WR	TQVWX I I	Oscillator frequency = 12 MHz Load capacitance on output pins = 80 pF	9, 10, 11	2Tosc-60	 	ns
Output data hold after WR 8/	TWXQX	See figure 3 	! !	 Tosc-25 		ns
End of WR to next ALE	TWXLH			 2Tosc-30 	 	ns
RD pulse width	 TRLRH 	 	! ! !	 3Tosc-30		ns
End of RD to next ALE	TRHLH			Tosc-30		ns
READY hold after CLKOUT edge <u>6</u> /	TCLYX		! ! !	0		ns
End of ALE to READY setup <u>6</u> /	TLLYV		 	-Tosc <u>1</u> /	 2Tosc-60 	ns
Non-ready time <u>6</u> /	 TYLYH				1,000	ns
Address valid to input data valid <u>6</u> /	TAVDV	 	 		5Tosc-100	ns
\overline{RD} active to input data valid $\underline{1}/\underline{6}/$	TRLDV	 	 	 	 3Tosc-70 	ns
End of RD to input data float 6/	 TRXDZ		 	 0 	Tosc-20	ns
End of ALE to READY <u>6</u> /	TLLYH			2Tosc+60 <u>1</u> /	4Tosc-60 <u>7</u> /	ns
	i	Į.	1	1.	1	l

Guaranteed but not tested. Guaranteed but not tested. IoL = 0.36 mA for all pins of P1, for P2.6 and P2.7, and for all pins of P3 and P4 when used as ports. I_{OL} = 2.0 mA for TXD, RXD (in serial port mode 0), PWM, CLKOUT, ALE, BHE, RD, WR, and all pins of HSO and P3 and P4 when used as external memory bus (ADO-AD15). I_{OH} = -20 μ A for all pins of P1, for P2.6 and P2.7. I_{OH} = -200 μ A for TXD, RXD (in serial port mode 0), PWM, CLKOUT, ALE, BHE, WR, and all pins of HSO and P3 and P4 when used as external memory bus (ADO-AD15). P3 and P4, when used as ports, have open-drain outputs. Analog conversion not in process. CLKOUT is directly generated as a divide by three of the oscillator. The period will be 270-270.

CLKOUT is directly generated as a divide by three of the oscillator. The period will be $3Tosc \pm 10$ ns if Tosc is constant and the rise and fall times on XTAL1 are less than 10 ns.

6/ Other system components must meet these specifications.
7/ If more than one wait state is desired, add "3Tosc" for each additional wait state.
8/ Due to test equipment limitation, actual tested values may differ from those specified, but specified limits are guaranteed.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER	SIZE		DWG NO. 85063		
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO		 REV A		PAGE 6	



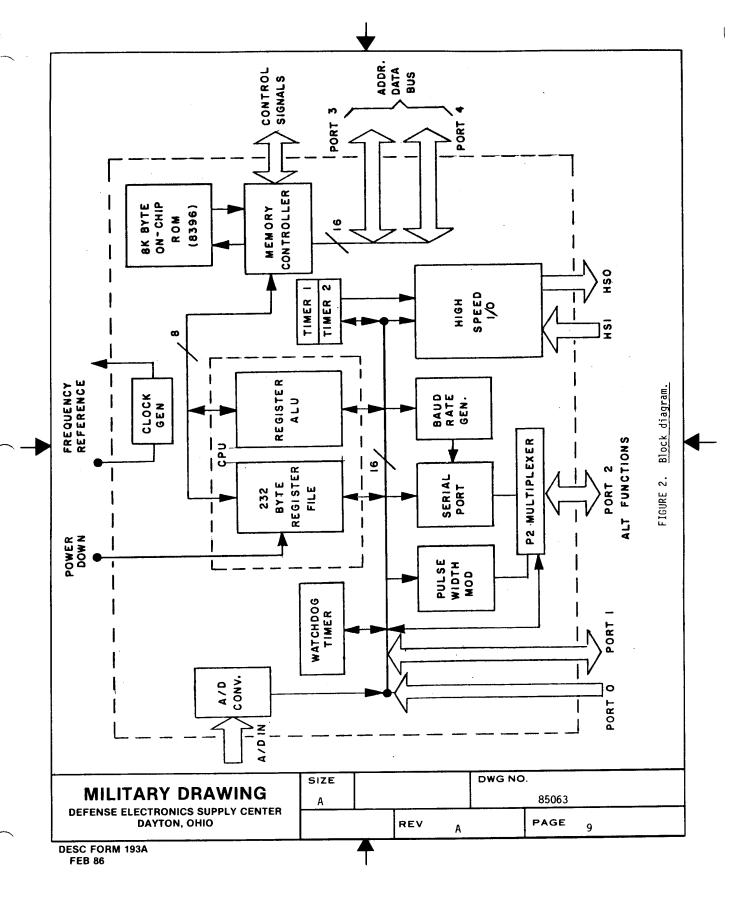
Symbo1	Inc	hes	 Millim 	eters
	Min	Max	Min	l Max
A	0.080	0.106	2.03	2.69
В	0.016	0.020	0.41	0.51
B ₁	0.040	10.060	1.02	1.52
B ₂	0.030	 0.040 	0.76	1.02
B ₃	0.005	0.020	0.13	0.51
С	0.008	0.012	0.20	0.31
D	1.640	1.870	41.66	47.50
01	0.935	0.970	23.75	24.64
D ₂	0.800	D BSC	20.32	2 BSC
e ₁	0.050	BSC	1.27	7 BSC
L	0.375	0.450	9.53	11.43
L ₁	0.040	0.060	1.02	1.52
i N	68	3	68	3
S	0.066	0.087 i	1.68	2.21
s ₁	0.050		1.27	

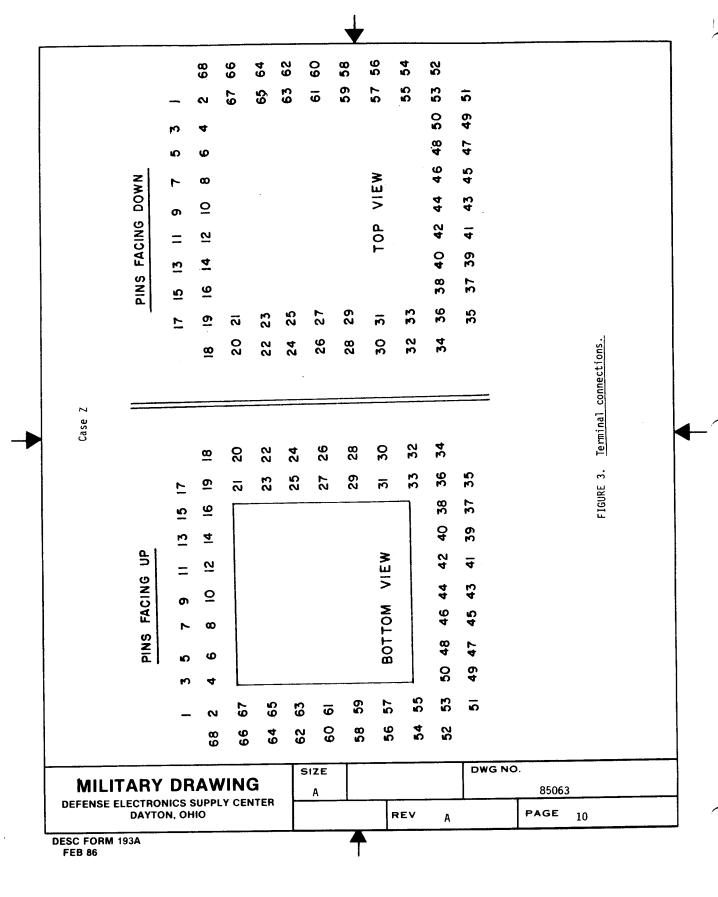
FIGURE 1. Case outline Y - Continued.

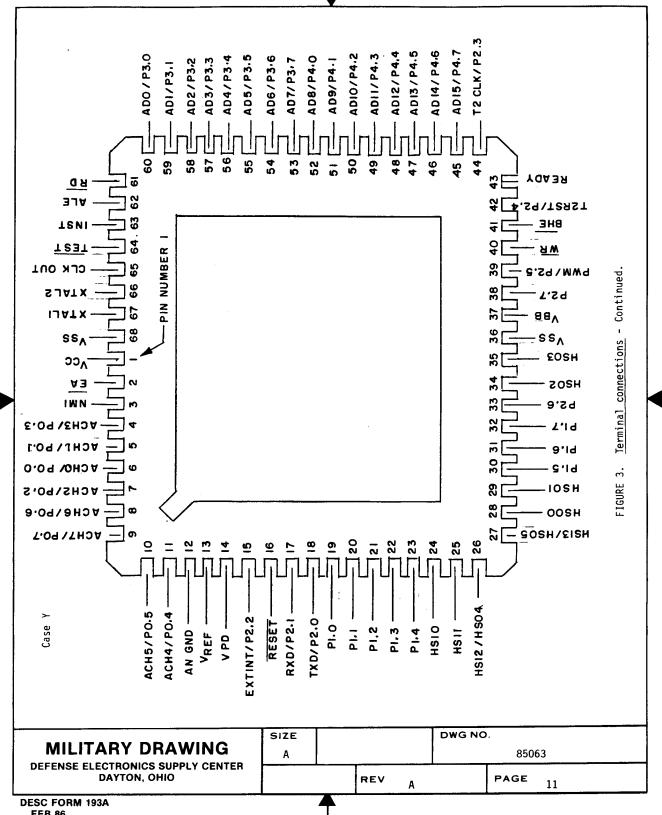
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO

SIZE
A
B5063

REV
A
PAGE 8







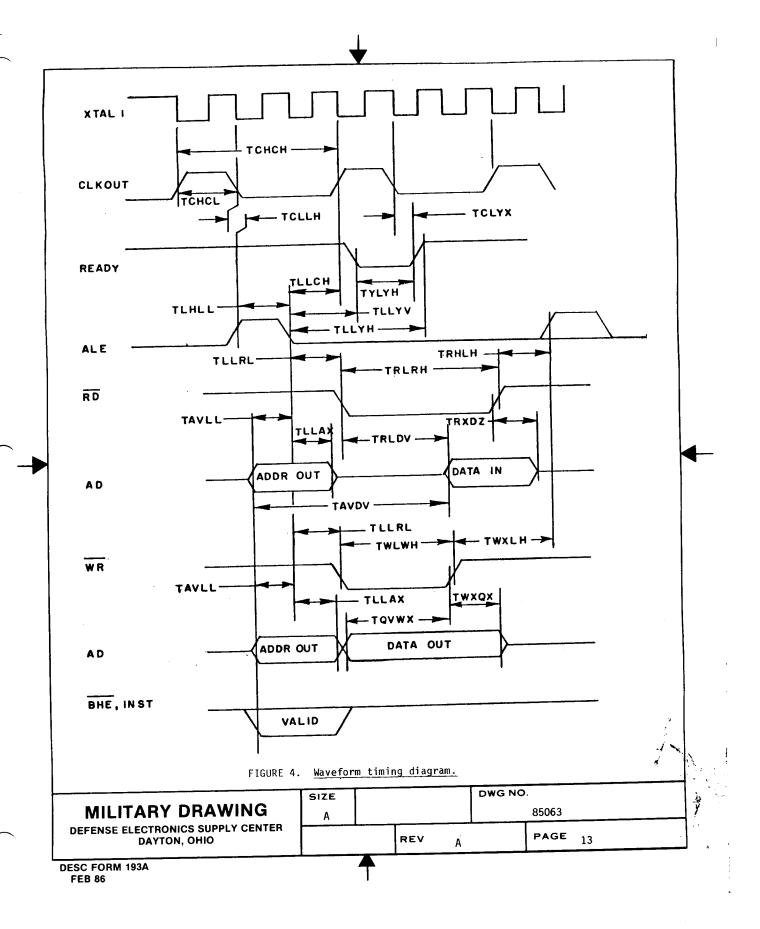
FEB 86

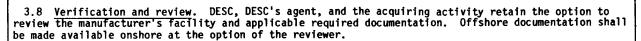
Case Y

Case Z	Case Y	Description	Case Z	Case Y	Description	Case Z	Case Y	Description
1	9	ACH7/PO.7	24	54	AD6/P3.6	47	31	P1.6
2	8	ACH6/PO.6	25	53	AD7/P3.7	48	30	P1.5
3	i 7	ACH2/PO.2	26	52	AD8/P4.0	49	29	HS0.1
4	6	ACHO/PO.O	27	51	AD9/P4.1	50	28	HS0.0
5	i š	ACH1/PO.1	28	50	AD10/P4.2	51	27	HSO.5/HSI.3
5 6 7	, -	ACH3/PO.3	29	49	AD11/P4.3	52	26	HSO.4/HSI.
ž	3 2	NMI	30	48	AD12/P4.4	53	25	HSI.1
8 9	2	EA	31	47	AD13/P4.5	54	24	HSI.0
ğ	1	VCC	32	46	AD14/P4.6	55	23	P1.4
10	68	VSS	33	45	! AD15/P4.7	56	22	P1.3
11	67	XTAL 1	34	44	1 T2CLK/P2.3	57	21	P1.2
12	66	XTAL 2	35	43	READY	58	20	P1.1
13	65	CLKOUT	36	42	T2RST/P2.4	59	19	P1.0
14	64	TEST	37	41	BHE	60	18	TXD/P2.0
15	63	INST	38	40	∤ WR	61	17	RXD/P2.1
16	62	ALE	39	39	PWM/P2.5	62	16	RESET
Ī7	61	RD	40	38	P2.7	63	15	EXTINT/P2.
18	60	ADO/P3.0	41	37	VBB	64	14	VPD
19	59	AD1/P3.1	42	36	VSS	65	13	VREF
20	58	AD2/P3.2	43	35	HS0.3	66	12	ANGND
21	57	AD3/P3.3	44	34	HSO.2	67	11	ACH4/PO.4
22	56	AD4/P3.4	45	33	P2.6	68	10	ACH5/PO.5
23	55	AD5/P3.5	46	32	I P1.7	1	1	1

FIGURE 3. Terminal connections - Continued.

MILITARY DRAWING	SIZE			DWG NO		
	Α				85063	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO		REV	A		PAGE	12





- 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 and method 5005 of MIL-STD-883, except as modified herein.
- 4.2 <u>Screening.</u> Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test (method 1015 of MIL-STD-883).
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inpsection shall be in accordance with method $\overline{5005}$ of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - c. Subgroup 4 (C_S measurement) shall be measured only for the initial test and after process or design changes which may affect capacitance.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE	CODE IDENT. NO.		DWG NO. 85063		
			REV Å		PAGE	14

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)			
Initial electrical parameters (method 5004)	±			
 Final electrical test parameters (method 5004) 	1 1*, 2, 3, 7, 8, 9, 10, 11			
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10, 11			
 Groups C and D end-point electrical parameters (method 5005) 	2, 8 (+125°C only), 10			

^{*} PDA applies to subgroup 1.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

MILITARY DRAWING	SIZE	CODE IDENT. NO.	DWG NO.
MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	A		85063
		REV A	PAGE 15

6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Yendor CAGE number	Vendor similar part number <u>1</u> /			
8506301ZX	34649	MG8097/B			
8506301YX	34649	MQ8097/B			

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

34649

Vendor name and address

Intel Corporation 5000 W. Williams Field Rd. Chandler, AZ 85224

MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	E A			DWG NO. 85063		
			REV		PAGE	16	